SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74LS175, SN74S174, SN74LS175, SN74S175, SN74S174, SN74LS175, SN74S174, SN74LS175, SN74S174, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74LS176, SN54LS176, SN

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'174, 'LS174, 'S174 . . . HEX D-TYPE FLIP-FLOPS '175, 'LS175, 'S175 . . . QUADRUPLE D-TYPE FLIP-FLOPS

- '174, 'LS174, 'S174 Contain Six Flip-Flops with Single-Rail Outputs
- '175, 'LS175, 'S175 Contain Four Flip-Flops with Double-Rail Outputs
- Three Performance Ranges Offered: See Table Lower Right
- Buffered Clock and Direct Clear Inputs
- Individual Data Input to Each Flip-Flop
- Applications include: Buffer/Storage Registers

Shift Registers
Pattern Generators

description

These monolithic, positive-edge-triggered flip-flops utilize TTL circuitry to implement D-type flip-flop logic. All have a direct clear input, and the '175, 'LS175, and 'S175 feature complementary outputs from each flip-flop.

Information at the D inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the clock input is at either the high or low level, the D input signal has no effect at the output.

These circuits are fully compatible for use with most TTL circuits.

FUNCTION TABLE (EACH FLIP-FLOP)

I	NPUTS		оит	PUTS
CLEAR	CLEAR CLOCK		Q	ā۲
L	X	Х	L	Н
н	1	н	н	L
н	1	L	L	Н
н	L	х	αo	$\bar{\alpha}_0$

H = high level (steady state)

L = low level (steady state)

X = irrelevant

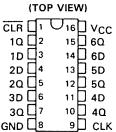
↑ = transition from low to high level

 ${\bf Q}_{\bf Q}$ = the level of ${\bf Q}$ before the indicated steady-state input conditions were established.

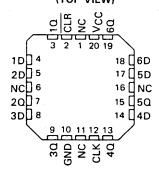
† = '175, 'LS175, and 'S175 only

	TYPICAL	TYPICAL
TYPES	MAXIMUM	POWER
11723	CLOCK	DISSIPATION
	FREQUENCY	PER FLIP-FLOP
174, 175	35 MHz	38 mW
'LS174, 'LS175	40 MHz	14 mW
'S174, 'S175	110 MHz	75 mW

SN54174, SN54LS174, SN54S174 . . . J OR W PACKAGE SN74174 . . . N PACKAGE SN74LS174, SN74S174 . . . D OR N PACKAGE



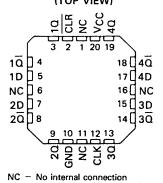
SN54LS174, SN54S174 . . . FK PACKAGE (TOP VIEW)



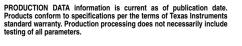
SN54175, SN54LS175, SN54S175 . . . J OR W PACKAGE SN74175 . . . N PACKAGE SN74LS175, SN74S175 . . . D OR N PACKAGE

> (TOP VIEW) U16 VCC CLR 1 10 🛮 2 15 40 10 □3 14 🛮 4 🗖 1D 🗆 4 13 4D 12 🛮 3D 2D 🗆 5 11 🛮 3 🗟 20 16 10 🛮 30 20 🗆 7 9 CLK

SN54LS175, SN54S175 . . . FK PACKAGE (TOP VIEW)



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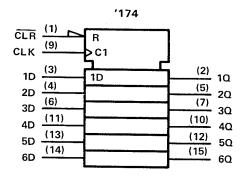


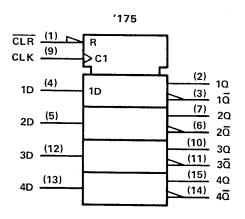


SN54174, SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175, SN74174, SN74LS174, SN74LS175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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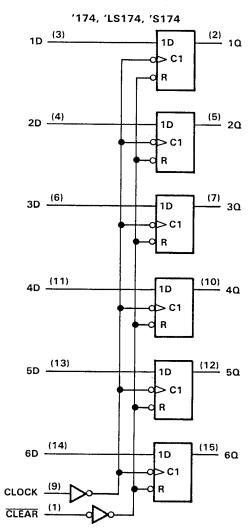
logic symbols†

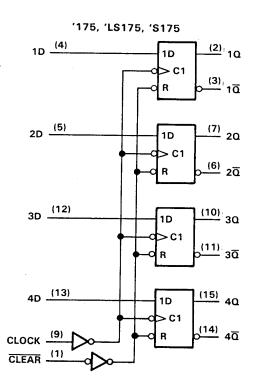




[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

logic diagrams (positive logic)





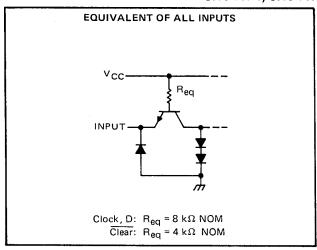
Pin numbers shown are for D, J, N, and W packages.

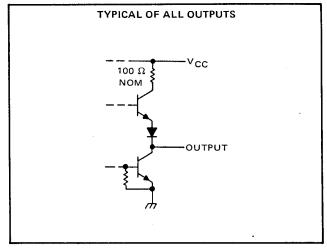


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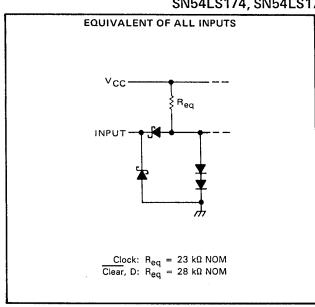
schematics of inputs and outputs

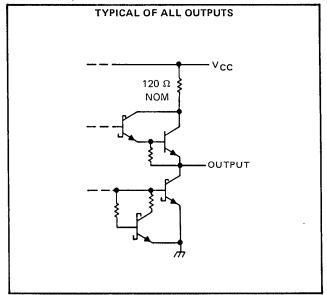
SN54174, SN54175, SN74174, SN74175



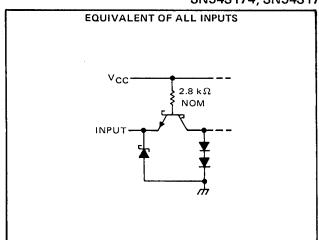


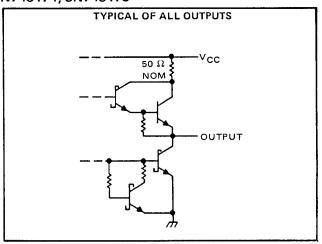
SN54LS174, SN54LS175, SN74LS174, SN74LS175





SN54S174, SN54S175, SN74S174, SN74S175







SN54174, SN54175, SN74174, SN74175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)			V
Input voltage		5.5	V
Operating free-air temperature range: SN5417	74, SN54175 Circuits		°C
SN7417	74, SN74175 Circuits	0°C to 70	°C
Storage temperature range			°C

recommended operating conditions

NOTE 1: Voltage values are with respect to network ground terminal.

		SN54	174, SN	54175	SN74	174, SN	74175	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-800			800	μΑ
Low-level output current, IOL				16			16	mA
Clock frequency, f _{clock}		0		25	0		25	MHz
Width of clock or clear pulse, t _W		20			20			ns
Setup time, t _{su}	Data input	20			20			ns
Setup time, t _{su}	Clear inactive-state	25			25			ns
Data hold time, t _h		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS [†]	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage		2			V
VIL	Low-level input voltage				0.8	>
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5	>
Vон	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -800 μA	2.4	3.4		٧
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4	٧
Ιį	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1	mA
ΊΗ	High-level input current	V _{CC} = MAX, V _I = 2.4 V			40	μΑ
IIL	Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6	mA
1	Chart in it and the	SN SN	54' -20		-57	^
los	Short-circuit output current §	V _{CC} = MAX	74' –18		-57	mA
laa	Cumple guerrant	VCC = MAX. See Note 2 '17	74	45	65	
1CC	Supply current	V _{CC} = MAX, See Note 2 /17	75	30	45	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device type.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}	Maximum clock frequency		25	35		MHz
tPLH	Propagation delay time, low-to-high-level output from clear (SN54175, SN74175 only)	C _L = 15 pF,		16	25	ns .
tPHL.	Propagation delay time, high-to-low-level output from clear	R_L = 400 Ω, See Note 3		23	35	ns
^t PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		20	30	ns
tPHL	Propagation delay time, high-to-low-level output from clock			24	35	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^\}ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

 $[\]$ Not more than one output should be shorted at a time.

SN54LS174, SN54LS175, SN74LS174, SN74LS175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)				 	 	 7 V
Input voltage			<i></i>	 	 	 7.V
Operating free-air temperature range:	SN54LS174,	SN54LS175 C	Circuits .	 	 	–55°C to 125°C
	SN74LS174,	SN74LS175 (Circuits .	 ·	 	 1.0° C to 70° C
Storage temperature range						-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN	154LS1	74	SN	174LS1	74	
		12	154LS1	75	SI	174LS1	75	UNIT
		WIŃ	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	٧
High-level output current, IOH				-400			-400	μА
Low-level output current, IOL				4			8	mA
Clock frequency, f _{clock}		0		30	0		30	MHz
Width of clock or clear pulse, t _W		20			20			ns
Setup time, t _{su}	Data input	20			20			ns
Setup time, t _{su}	Clear inactive-state	25			25			ns
Data hold time, t _h		5			5			ns
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TES	T CONDITIONS	t	_	N54LS1 N54LS1		_	N74LS N74LS		UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage				2			2			٧
v_{IL}	Low-level input voltage						0.7			0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I ₁ = -18 mA				-1.5			-1.5	V
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, , I _{OH} = -400 μ,	Α	2.5	3.5		2.7	3.5		٧
V	Louise outros vales -	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	
VOL	Low-level output voltage	VIL = VIL max	•	IOL = 8 mA					0.35	0.5	٧
łį	Input current at maximum input voltage	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mA
Чн	High-level input current	V _{CC} = MAX,	V _I = 2.7 V			· · · · · ·	20			20	μА
IJĽ	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V				-0.4			-0.4	mA
los	Short-circuit output current §	V _{CC} = MAX			-20		-100	-20		-100	mA
loo	Supply current	V MAY	Coo Note 2	'LS174		16	26		16	26	1
¹cc	Supply culterit	V _{CC} = MAX,	See Note 2	'LS175		11	18		11	18	mA

¹ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS		'LS174			'LS175		
FARAMETER	TEST CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
f _{max} Maximum clock frequency		30	40		30	40		MHz
tplH Propagation delay time, low-to-high-level output from clear	C _L = 15 pF,					20	30	ns
tphl Propagation delay time, high-to-low-level output from clear	$R_L = 2 k\Omega$,		23	35		20	30	ns
tPLH Propagation delay time, low-to-high-level output from clock	See Note 3		20	30		13	25	ns
tpHL Propagation delay time, high-to-low-level output from clock			21	30		16	25	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $^{^{\}dagger}$ \$\frac{1}{4}\$All typical values are at $V_{CC} = 5 \text{ V}$, $T_{A} = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to clock.

SN54S174, SN54S175, SN74S174, SN74S175 HEX/QUADRUPLE D-TYPE FLIP-FLOPS WITH CLEAR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)									 7	V
Input voltage									 5.5	V
Operating free-air temperature rang	e: SN5	4S174	, SN54S	175 Circuits					-55°C to 125°	С
-	SN7	4S174	, SN74S	175 Circuits					 . 0°C to 70°	C
Storage temperature range									65°C to 150°	'C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN549	174, SN	54S175	SN74S	174, SN	74S175	LINIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-1			-1	mA
Low-level output current, IOL				20			20	mA
Clock frequency, f _{clock}		0		75	0		75	MHz
Pulso width +	Clock	7			7			
Pulse width, t _W	Clear	10			10			ns
Cotur diana d	Data input	5			5			
Setup time, t _{su}	Clear inactive-state	5			5			ns
Data hold time, t _h		3			3			ns
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
v_{IK}	Input clamp voltage	V _{CC} = MIN, I _I = -18 mA				-1.2	V
	High level automaticalisms	V _{CC} = MIN, V _{IH} = 2 V,	SN54S'	2.5	3.4		V
VOH	High-level output voltage	V _{IL} = 0.8 V, I _{OH} = -1 mA	SN74S'	2.7	3.4) V
V	Low level output voltage	V _{CC} = MIN, V _{IH} = 2 V,				0.5	V
VOL	.ow-level output voltage	V _{IL} = 0.8 V, I _{OL} = 20 mA			0.5	1	
Ц	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V				1	mA
ЧΗ	High-level input current	V _{CC} = MAX, V ₁ = 2.7 V				50	μΑ
11L	Low-level input current	V _{CC} = MAX, V _I = 0.5 V				-2	mA
los	Short-circuit output current §	V _{CC} = MAX		-40		-100	mA
la-	Supply surrent	VMAY See Note 2	′174		90	144	mA
Icc	Supply current	V _{CC} = MAX, See Note 2	′175		60	96] '''A

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable device

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}	Maximum clock frequency		75	110		MHz
tPLH	Propagation delay time, low-to-high-level $\overline{\mathbb{Q}}$ output from clear (SN54S175, SN74S175 only)	C _L = 15 pF,		10	15	ns
tPHL.	Propagation delay time, high-to-low-level Q output from clear	$R_L = 280 \Omega$, See Note 3		13	22	ns
^t PLH	Propagation delay time, low-to-high-level output from clock	See Note 3		8	12	ns
†PHL	Propagation time, high-to-low-level output from clock			11.5	17	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C. § Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

NOTE 2: With all outputs open and 4.5 V applied to all data and clear inputs, ICC is measured after a momentary ground, then 4.5 V, is





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/01702BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/01702BFA	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
JM38510/07105BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07105BEA	Samples
JM38510/07105BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07105BFA	Samples
JM38510/07106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07106BEA	Samples
JM38510/30106B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30106B2A	Samples
JM38510/30106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30106BEA	Samples
JM38510/30106BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30106BFA	Samples
JM38510/30107B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30107B2A	Samples
JM38510/30107BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30107BEA	Samples
JM38510/30107BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30107BFA	Samples
M38510/07105BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07105BEA	Samples
M38510/07105BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07105BFA	Samples
M38510/07106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 07106BEA	Samples
M38510/30106B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30106B2A	Samples
M38510/30106BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30106BEA	Samples
M38510/30106BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30106BFA	Samples
M38510/30107B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30107B2A	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/30107BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30107BEA	Samples
M38510/30107BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30107BFA	Samples
SN54175J	OBSOLETE	E CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SN54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS174J	Samples
SN54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS175J	Samples
SN54S174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S174J	Samples
SN54S175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54S175J	Samples
SN74174N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74175N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS174D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS174	Samples
SN74LS174DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS174	Samples
SN74LS174DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS174	Samples
SN74LS174J	OBSOLETE	E CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS174N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS174N	Samples
SN74LS174N3	OBSOLETE	E PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS174NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS174N	Samples
SN74LS174NSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS174	Samples
SN74LS175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS175	Samples
SN74LS175DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS175	Samples
SN74LS175DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS175	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70	, ,	
SN74LS175N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS175N	Samples
SN74LS175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS175NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS175N	Samples
SN74LS175NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS175	Samples
SN74S174J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74S174N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70	SN74S174N	
SN74S174N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S175D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	S175	Samples
SN74S175DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI	0 to 70		
SN74S175N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S175N	Samples
SN74S175N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S175NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74S175N	Samples
SNJ54175J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54175W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 174FK	Samples
SNJ54LS174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS174J	Samples
SNJ54LS174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS174W	Samples
SNJ54LS175FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 175FK	Samples
SNJ54LS175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS175J	Samples
SNJ54LS175W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS175W	Samples
SNJ54S174FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125	SNJ54S 174FK	



PACKAGE OPTION ADDENDUM

10-Jul-2016

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SNJ54S174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S174J	Samples
SNJ54S174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S174W	Samples
SNJ54S175J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54S175J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Jul-2016

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54175, SN54LS174, SN54LS175, SN54S175, SN54S175, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74LS175, SN74S175, SN74LS175, SN74LS175,

- Catalog: SN74175, SN74LS174, SN74LS175, SN74S174, SN74S175
- Military: SN54175, SN54LS174, SN54LS175, SN54S174, SN54S175

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

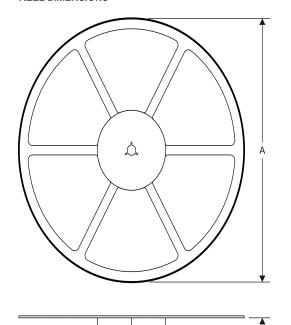
PACKAGE MATERIALS INFORMATION

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TAPE DIMENSIONS

TAPE AND REEL INFORMATION

REEL DIMENSIONS





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS174DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS174NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS175DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS175NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS174DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS174NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS175DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS175NSR	SO	NS	16	2000	367.0	367.0	38.0

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